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UNITED STATES PATENT AND TRADEMARK OFFICE  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/904,906	07/16/2001	2825	790	740756-2332	6	20	4

CONFIRMATION NO. 4431

22204  
NIXON PEABODY, LLP  
8180 GREENSBORO DRIVE  
SUITE 800  
MCLEAN, VA 22102

## FILING RECEIPT



\*OC00000006404360\*

Date Mailed: 08/09/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Takeshi Fukada, Atsugi-shi, JAPAN;  
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Satoshi Teramoto, Atsugi-shi, JAPAN;  
*Sakama*

## Domestic Priority data as claimed by applicant

THIS APPLICATION IS A DIV OF 09/294,338 04/20/1999 PAT 6,268,631  
WHICH IS A DIV OF 08/462,773 06/05/1995 PAT 5,929,487  
WHICH IS A DIV OF 08/311,275 09/23/1994 PAT 5,674,304

## Foreign Applications

JAPAN 5-279029 10/12/1993

If Required, Foreign Filing License Granted 08/08/2001

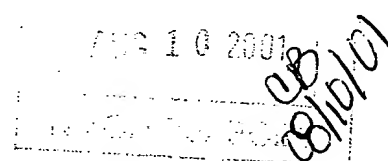
Projected Publication Date: 11/15/2001

Non-Publication Request: No

Early Publication Request: No

## Title

Glass substrate assembly, semiconductor device and method of heat-treating glass substrate



**Preliminary Class**  
257

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**Data entry by : LE, THANH-LAN**

**Team : OIPE**

**Date: 08/09/2001**

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Title 35, United States Code, Section 184  
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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**PLEASE NOTE the following information about the Filing Receipt:**

- The articles such as "a," "an" and "the" are not included as the first words in the title of an application. They are considered to be unnecessary to the understanding of the title.
- The words "new," "improved," "improvements in" or "relating to" are not included as first words in the title of an application because a patent application, by nature, is a new idea or improvement.
- The title may be truncated if it consists of more than 500 characters (letters and spaces combined).
- The docket number allows a maximum of 25 characters.
- If your application was submitted under 37 CFR 1.10, your filing date should be the "date in" found on the Express Mail label. If there is a discrepancy, you should submit a request for a corrected Filing Receipt along with a copy of the Express Mail label showing the "date in."
- The title is recorded in sentence case.

Any corrections that may need to be done to your Filing Receipt should be directed to:

Assistant Commissioner for Patents  
Office of Initial Patent Examination  
Customer Service Center  
Washington, DC 20231



Attorney Docket No. 0756-2332

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

) Group Art Unit: 2825

Takeshi FUKADA et al.

) Examiner: L. Malsawma

Serial No. 09/904,906

) CERTIFICATE OF MAILING

Filed: July 16, 2001

) I hereby certify that this correspondence is  
) being deposited with the United States Postal  
) Service with sufficient postage as First Class  
) Mail in an envelope addressed to:  
) Commissioner for Patents, P.O. Box 1450,  
) Alexandria, VA 22313-1450, on  
3.31.2004

For: GLASS SUBSTRATE ASSEMBLY,

SEMICONDUCTOR DEVICE AND

METHOD OF HEAT-TREATING

GLASS SUBSTRATE

) Adelle M. Stamper

**SUBMISSION OF CORRECTED APPLICATION DATA SHEET**

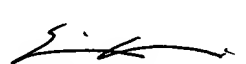
**AND REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT**

Honorable Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Inventor Mitsunori Sakama's name is misspelled on the Application Data Sheet originally filed in the subject application. As a result of this error, Mr. Sakama's name is also misspelled on the Official Filing Receipt (copy enclosed). Applicant is hereby notifying the U.S.P.T.O. of this error and requests correction by submission of the enclosed Supplemental Application Data Sheet. In view of the above, it is requested that a Corrected Filing Receipt be issued. The fee in the amount of \$25.00 is enclosed.

Respectfully submitted,

  
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## Application Data Sheet

### Application Information

Application number::

Filing Date::

Application Type::

Subject Matter::

Title ::

Regular

Utility

GLASS SUBSTRATE  
ASSEMBLY,  
SEMICONDUCTOR DEVICE  
AND METHOD OF HEAT-  
TREATING GLASS  
SUBSTRATE

Attorney Docket Number::

0756-2332

Total Drawing Sheets::

6

Small Entity?::

No

### Applicant Information

Applicant Authority Type::

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Primary Citizenship Country::

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## Representative Information

Representative Customer Number:: 31780

## Domestic Priority Information

Application ::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Divisional	09/294,338	04/20/1999
09/294,338	Divisional	08/462,773	06/05/1995
08/462,773	Divisional	08/311,275	09/23/1994

## Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	05-279029	10/12/1993	Yes

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